















ESD

TVS

MOS

LDO

Diode

Sensor

DC-DC

Product Specification

Domestic Part Number	MB1S - MB10S
Overseas Part Number	MB1S - MB10S
▶ Equivalent Part Number	MB1S - MB10S





■ 1A Surface Mount Glass Passivated Bridge Rectifier

■ Features

Glass Passivated Chip Junction
Reverse Voltage - 100 to 1000 V
Forward Current - 1 A
High Surge Current Capability
Designed for Surface Mount Application



■ Simplified outline(MBS)

Pinning

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

■ Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MB1S	MB2S	MB4S	MB6S	MB8S	MB10S	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 50 °C	Io	1.0						А
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	35					А	
Maximum Forward Voltage at 1.0 A	V _F	1.1				٧		
Maximum DC Reverse Current @T _A =25 °C at Rated DC Blocking Voltage @T _A =125 °C	I _R	5 40					μA	
Typical Junction Capacitance (Note1)	C _j	13				pF		
Typical Thermal Resistance (Note2)	R _{øJA} R _{øJL}	85 30				°C/W		
Operating and Storage Temperature Range	T_{j},T_{stg}	-55 ~ +150				°C		

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with $4 \times (5 \times 5 \text{mm}^2)$ copper pad.



Fig.1 Average Rectified Output Current Derating Curve

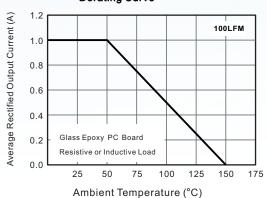


Fig.2 Typical Reverse Characteristics

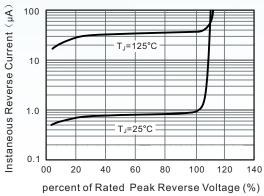


Fig.3 Typical Instaneous Forward Characteristics

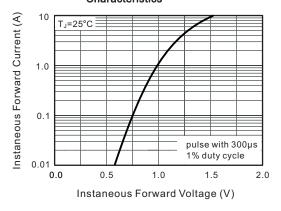


Fig.4 Typical Junction Capacitance

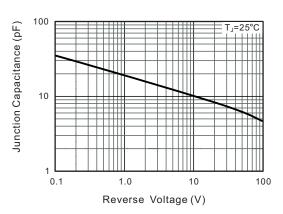
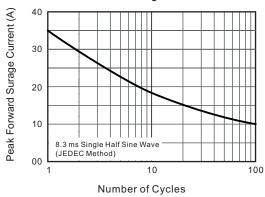
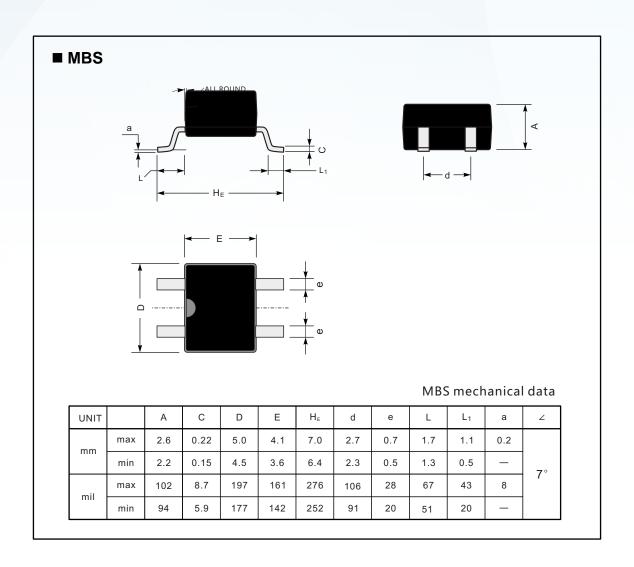


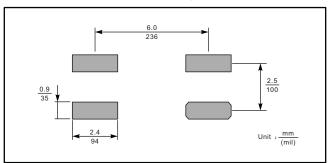
Fig.5 Maximum Non-Repetitive Peak Forward Surage Current







The recommended mounting pad size





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